

## 1.0Amp Fast Recovery Surface Mounted Rectifiers

SOD123FL  

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
260°C/10 seconds at terminals

### Mechanical Data

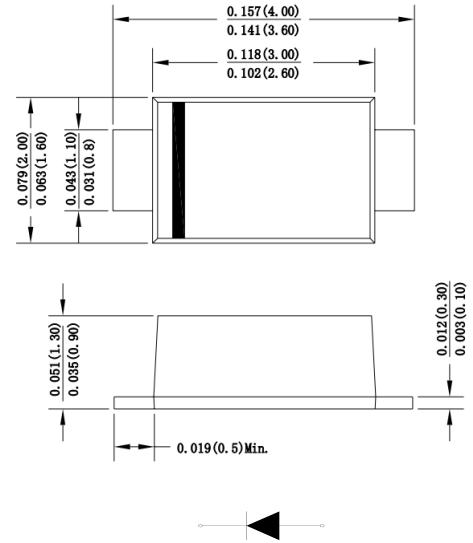
**Case** : Molded plastic body

**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity** : Polarity symbol marking on body

**Mounting Position** : Any

**Weight** : 0.0007 ounce, 0.02 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	F1	F2	F3	F4	F5	F6	F7	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	30.0							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	1.30							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	2.0 200							$\mu\text{A}$
Maximum reverse recovery time(Note 1)	$T_{rr}$	150			250		500		ns
Typical junction capacitance (Note2)	$C_J$	9.0							pF
Typical thermal resistance	$R_{qJA}$	85.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

**Note:** 1.Reverse recovery time test condition:  $I_F=0.5\text{A}$   $I_R=1.0\text{A}$   $I_{rr}=0.25\text{A}$   
2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

## Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

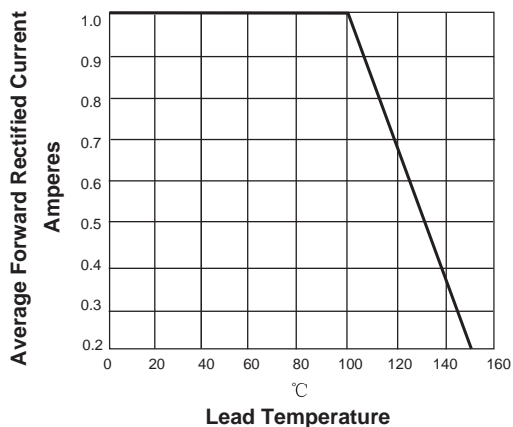


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

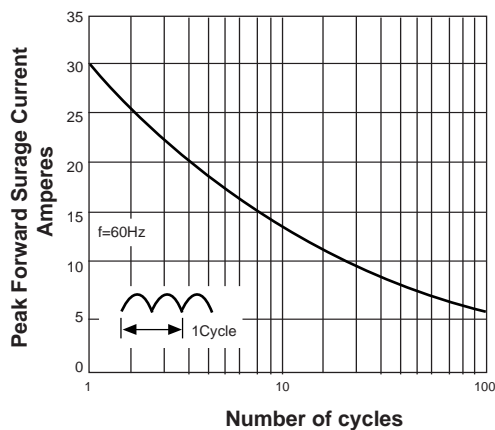


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

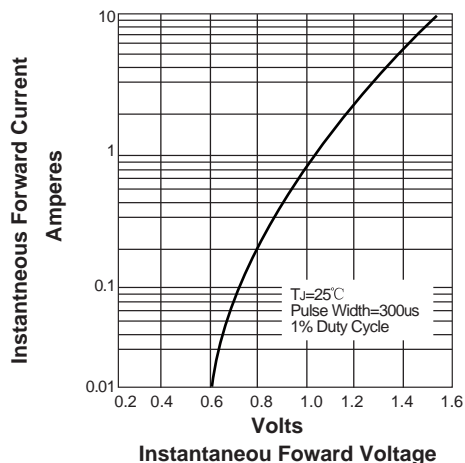
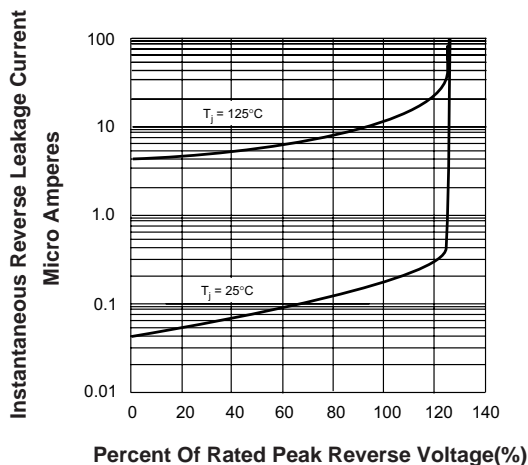
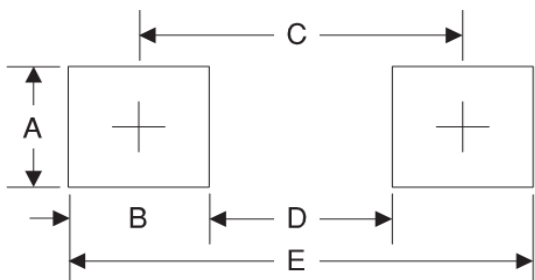


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

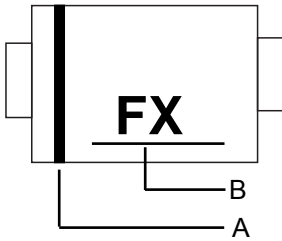


## Suggested Pad Layout



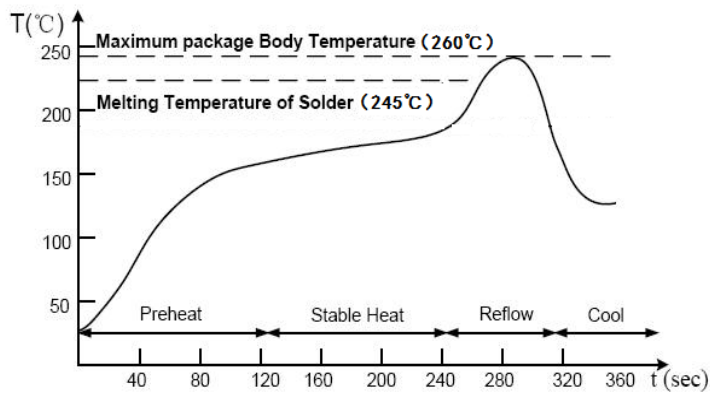
Symbol	Unit (mm)	Unit (inch)
A	1.2	0.048
B	1.15	0.045
C	3.10	0.122
D	1.95	0.077
E	4.25	0.167

## Marking



Symbol	Explanation
A	Color Band Denotes Cathode
B	Product Name, X : 1.2.....7

## Suggested Soldering Temperature Profile

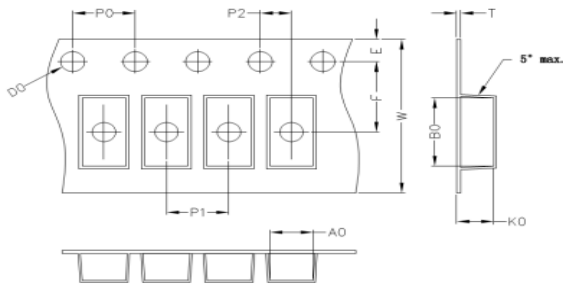


### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

### Carrier Dimension(mm)



A0	B0	K0	D0	E	F
2.15	3.95	1.35	1.55	1.75	3.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	8	0.1

### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SOD123FL	7'	178	3	180	15	380*200*200	150